



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Kuniko Kikuta

Serial No.: 09/584,739

Group Art Unit: 2814

Filed: June 1, 2000

Examiner: Quach, Tuan N.

For: COPPER-ALLOY INTERCONNECTION LAYER

Honorable Commissioner of Patents
Washington, D.C. 20231

BOX AF

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GP2814
10/18(N.E)
T-Step toe
9/24/02
M. Brunson
10/25/02

AMENDMENT UNDER 37 C.F.R. §1.116

Sir:

In response to the Office Action dated **July 2, 2002**, please amend the above-identified application as follows:

*Do not enter
TU*

IN THE CLAIMS:

9/30/02
Please amend the following claims:

Sept. 07
1. (Amended) An electrically conductive layer comprising:

B1
a copper alloy which includes at least one of Bi, Sb, and Ti at not less than 0.1 percent by weight,

wherein said copper alloy has a melting point less than copper.

Sept. 07
22. (Amended) A semiconductor device comprising:

a semiconductor substrate;
an insulation layer over said semiconductor substrate, and said insulation layer having a trench groove;

a barrier metal layer on a bottom and side walls of said trench groove; and

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